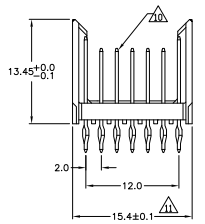
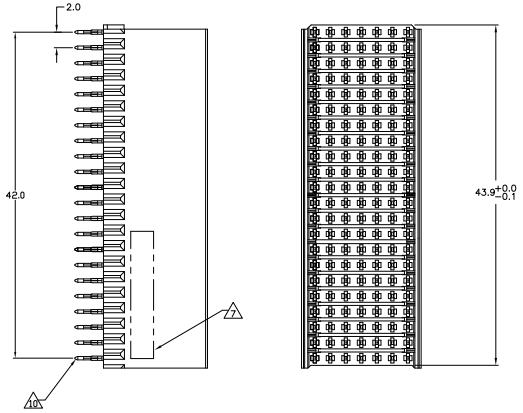


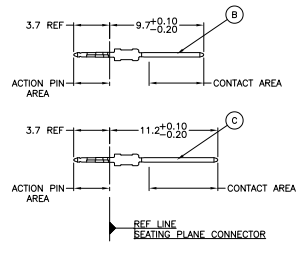
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REV	DATE	DESCRIPTION	BY	APP'D
00				
E2		REV PER EDR-10-00011	CLAM2010	JY SY

**CONNECTOR ASSEMBLY  
EXAMPLARY LOADED**



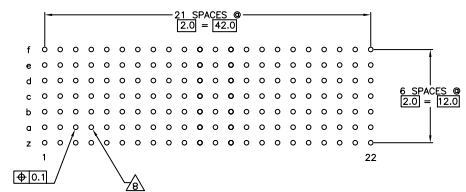
**CONTACT DIMENSIONS**  
SCALE 5:1



**CONTACT LAYOUT**

	z	a	b	c	d	e	f
1	C	B	B	B	B	B	C
2	C	B	B	B	B	B	C
3	C	B	B	B	B	B	C
4	C	B	B	B	B	B	C
5	C	B	B	B	B	B	C
6	C	B	B	B	B	B	C
7	C	B	B	B	B	B	C
8	C	B	B	B	B	B	C
9	C	B	B	B	B	B	C
10	C	B	B	B	B	B	C
11	C	B	B	B	B	B	C
12	C	B	B	B	B	B	C
13	C	B	B	B	B	B	C
14	C	B	B	B	B	B	C
15	C	B	B	B	B	B	C
16	C	B	B	B	B	B	C
17	C	B	B	B	B	B	C
18	C	B	B	B	B	B	C
19	C	B	B	B	B	B	C
20	C	B	B	B	B	B	C
21	C	B	B	B	B	B	C
22	C	B	B	B	B	B	C

**RECOMMENDED PCB-HOLE LAYOUT**  
COMPONENT SIDE SHOWN



**PLATED THRU HOLES PARAMETERS**  
REFERENCE APPLICATION SPECIFICATION

△△△△	3-188835-1
△△△△	3-188835-0
△△△△	1-188835-9
△△△△	188835-9
△△△△	188835-4
△△△△	188835-1
△△△△	PART NUMBER

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1	108-19082					
2	114-19029					
3						
4						
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 BY THE ELECTRONICS CORPORATION ALL RIGHTS RESERVED

REV	DATE	DESCRIPTION	BY	APP
AD	00			
		SEE SHEET 1		

- △ MATERIAL:  
CONTACT: PHOSPHOR BRONZE.  
HOUSING: GLASS-FILLED POLYESTER.
- △ GENERAL PLATING SPECIFICATION: UNDERPLATING  
(ENTIRE CONTACT): 1.27μm MIN NICKEL AND ACTION  
PIN: 0.5μm MIN TIN/LEAD.  
FOR PLATING OF MATING SURFACES SEE APPLICABLE  
SPECIFICATION REFERENCE FOR EACH DASH NUMBER.
- △ CONFORMS TO ALL TESTING ACCORDING TO IEC 61076-4-101  
PERFORMANCE LEVEL 2.
- △ CONFORMS TO ALL TESTING ACCORDING TO IEC 61076-4-101  
PERFORMANCE LEVEL 1.
- △ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL 3,  
CENTRAL OFFICE APPLICATIONS.
- △ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL 3,  
UNCONTROLLED ENVIRONMENT APPLICATIONS.
- △ CONNECTOR MARKED WITH PART NUMBER AND DATE CODE.  
ADDITIONAL CHARACTERS OR MARKINGS, AS WELL AS THE LOCATION OF THE MARKINGS,  
MAY BE ADDED FOR TRACEABILITY BASED UPON MANUFACTURERS DISCRETION.
- △ PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID  
PATTERN DEFINED BY CONTACT LAYOUT.
- △ FOR ACTUAL PIN LOADING SEE "CONTACT LAYOUT".
- △ FOR ACTUAL PIN DIMENSIONS SEE "CONTACT DIMENSIONS".
- △ TO BE MEASURED AT BOTTOM OF SHROUD.
- △ CONNECTOR LUBRICATED WITH BELCORE APPROVED LUBRICANT,  
TECHNICAL REFERENCE: TR-NWT-001217 ISSUE 1, SEP 1992.
- △ 0.76μm MIN GOLD PLATING AT MATING SURFACES.

THIS DRAWING IS A CONTROLLED DOCUMENT.		REVISED	DATE	Tyco Electronics Corporation Harrisburg, Pa 17105-2608	
DESIGNED BY	APPROVED BY	DESIGNED BY	DATE	MALE ASSEMBLY, 2-PACK 2mm HM, TYPE B	
mm	mm	mm	mm	108-19082	
mm	mm	mm	mm	114-19029	
mm	mm	mm	mm	CUSTOMER DRAWING	
mm	mm	mm	mm	A100779G-188835	
mm	mm	mm	mm	TYP 4:1	
mm	mm	mm	mm	2 2	
mm	mm	mm	mm	E2	